

it is difficult to cut the short ring with a laser beam in the final step. In particular, the short ring is cut together with the substrates along a common plane. As shown in Fig. 6, after the cutting, the end surfaces of the substrates are exposed. If static charges are produced on the exposed end surface after the cutting, the internal pixel TFTs will be destroyed, thus making the display device defective. Indicated by 507 is the counter substrate. Indicated by 508 is a sealant material. Indicated by 503 is a liquid crystal material. Indicated by 504 is a bus line. Indicated by 505 is the TFT substrate. Indicated by 506 are the exposed end surfaces.--

In the Claims:

Please cancel claims 65-68.

Please amend the claims as follows.

G1
Sub H5
17. (Amended) An active matrix liquid crystal display comprising:
a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;
G2
driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;
a bus line provided over said TFT substrate and connected with at least one of said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a nonconductive or weakly conductive material applied or adhesively bonded to a side edge of said counter substrate and a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and inside said side edge of said counter substrate and said side edge of said TFT substrate; and

a control circuit comprising a semiconductor chip provided under and in contact with said sealing material for controlling said driver circuit.

G2
cont.
Subst. 2
21. (Amended) An active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

G3
a bus line provided over said TFT substrate and connected with at least one of said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a nonconductive or weakly conductive material applied or adhesively bonded to a side edge of said counter substrate and a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and inside said side edge of said counter substrate and said side edge of said TFT substrate; and

a control circuit comprising a semiconductor chip provided under and in contact with said sealing material for controlling said driver circuit.

G 2
G 3 22. (Amended) An active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

a bus line provided over said TFT substrate and connected with at least one of said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a nonconductive or weakly conductive material applied or adhesively bonded to a side edge of said counter substrate and a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and inside said side edge of said counter substrate and said side edge of said TFT substrate, said sealing material being provided outside at least said pixel TFTs; and

a control circuit comprising a semiconductor chip provided under and in contact with said sealing material for controlling said driver circuit.

23. (Amended) An active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

G3 driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

a bus line provided over said TFT substrate and connected with at least one of said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a nonconductive or weakly conductive material applied or adhesively bonded to a side edge of said counter substrate and a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and inside said side edge of said counter

substrate and said side edge of said TFT substrate, said sealing material being provided outside said pixel TFTs and said driver TFTs; and

a control circuit comprising a semiconductor chip provided under and in contact with said sealing material for controlling said driver circuit.

24. (Amended) A method of fabricating an active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

G³
driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

a bus line provided over said TFT substrate and connected with at least one of said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and outside at least said pixel TFTs; and

a control circuit comprising a semiconductor chip provided under and in contact with said sealing material for controlling said driver circuit,

said method comprising:

cutting said TFT substrate and said counter substrate outside said sealing material having said control circuit under and in contact with said sealing material; and

applying or adhesively bonding a nonconductive or weakly conductive material to the cut side edge ¹¹² of said TFT substrate and the cut side edge ¹¹² of said counter substrate.

25. (Amended) A method of fabricating an active matrix liquid crystal display comprising:

a plurality of pixel TFTs arranged in rows and columns over a TFT substrate and arrayed in a matrix;

driver TFTs formed over said TFT substrate and forming a driver circuit for driving said pixel TFTs;

G3
a bus line provided over said TFT substrate and connected with at least one of said pixel TFTs;

a layer of a liquid crystal material with which said pixel TFTs and driver TFTs are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate and outside said pixel TFTs and said driver TFTs; and

a control circuit comprising a semiconductor chip provided under and in contact with said sealing material for controlling said driver circuit,

said method comprising:

cutting said TFT substrate and said counter substrate outside
said sealing material having said control circuit under and in
contact with said sealing material; and

G3
cont. applying or adhesively bonding a nonconductive or weakly
conductive material to the cut side edge of said TFT substrate
and the cut side edge of said counter substrate.

61. (Amended) A semiconductor device comprising:

G4
Subfix
a pixel TFT provided over a TFT substrate comprising a glass;
a counter substrate located opposite to said TFT substrate;
a bus line provided over said TFT substrate and connected
with said pixel TFT, said bus line having a part located
adjacent to a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and
said counter substrate; and

a nonconductive material applied to a side edge of said
counter substrate and said side edge of said TFT substrate and
said part of said bus line,

wherein said nonconductive material is provided on an outer
side of said sealing material.

62. (Amended) A semiconductor device comprising:

a pixel TFT provided over a TFT substrate comprising a glass;

a counter substrate located opposite to said TFT substrate;
a bus line provided over said TFT substrate and connected
with said pixel TFT, said bus line having a part located
adjacent to a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and
said counter substrate; and

a weakly conductive material applied to a side edge of said
counter substrate and said side edge of said TFT substrate and
said part of said bus line,

wherein said weakly conductive material is provided on an
outer side of said sealing material.

G 4

63. (Amended) A semiconductor device comprising:

a pixel TFT provided over a TFT substrate comprising a glass;
~~a driver TFT provided over said TFT substrate;~~
a layer of a liquid crystal material with which said pixel
TFT and said driver TFT are in contact directly or via a thin
film;

a counter substrate located opposite to said TFT substrate
with said layer of the liquid crystal material therebetween;

a bus line provided over said TFT substrate and connected
with said pixel TFT, said bus line having a part located
adjacent to a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate; and

a nonconductive material applied to a side edge of said counter substrate and said side edge of said TFT substrate and said part of said bus line,

wherein said nonconductive material is provided on an outer side of said sealing material.

64. (Amended) A semiconductor device comprising:

a pixel TFT provided over a TFT substrate comprising a glass;

a driver TFT provided over said TFT substrate;

G4
a layer of a liquid crystal material with which said pixel TFT and said driver TFT are in contact directly or via a thin film;

a counter substrate located opposite to said TFT substrate with said layer of the liquid crystal material therebetween;

a bus line provided over said TFT substrate and connected with said pixel TFT, said bus line having a part located adjacent to a side edge of said TFT substrate;

a sealing material provided between said TFT substrate and said counter substrate; and